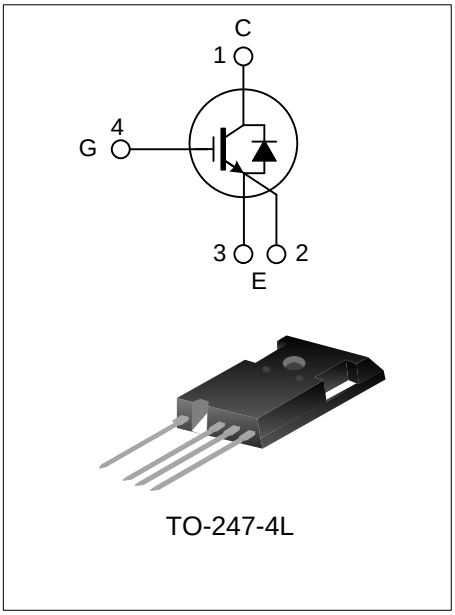
75A, 650V FIELD STOP IGBT

DESCRIPTION

SGT75T65SDM1P4 adopts Field Stop III IGBT technology, offer the optimum performance for induction Heating, UPS, SMPS and PFC application.



TO-247-4L

FEATURES

- 75A, 650V, $V_{CE(sat)(typ.)}$=1.65V@I_C=75A
- Low conduction loss
- Fast switching
- High input impedance

NOMENCLATURE

SGT 75 T 65 S D M 1 P4

IGBT series

Current, 70: 70A

N : N Channel
NE : N-channel planar gate with ESD
T : Field Stop 3/4
U : Field Stop 4+
V : Field Stop 5
W: Field Stop 6
X : Field Stop 7

Voltage, 65: 650V
120: 1200V

Package
P7 : TO-247-3L
F: TO-220F-3L

1,2,3··· : Version No.

Blank: Standard diode
M : Standard Diode, full range
R : Rapid Diode
B : Rapid Diode, full range
S : Soft Diode, full range

D : Packaged with fast recovery diode
R : RC IGBT

L: Ultra low switching,
recommended frequency ~2kHz;
Q: Low switching,
recommended frequency 2~20kHz;
S: Standard frequency,
recommended frequency 5~40kHz;
F: Fast switching,
recommended frequency10~60kHz;
UF: Ultra fast switching,
recommended frequency 40kHz~.

ORDERING INFORMATION

Part No.	Package	Marking	Hazardous Substance Control	Packing Type
SGT75T65SDM1P4	TO-247-4L	75T65SDM1	Pb free	Tube

ABSOLUTE MAXIMUM RATINGS (T_C=25°C UNLESS OTHERWISE NOTED)

Characteristics		Symbol	Ratings	Units
Collector to Emitter Voltage		V_{CE}	650	V
Gate to Emitter Voltage		V_{GE}	±20	V
Transient Gate to Emitter Voltage (t_p≤10μs, D<0.010)		V_{GE}	±30	V
Collector Current	T_C=25°C	I_C	150	A
	T_C=100°C		75	
Pulsed Collector Current		I_{CM}	300	A
Diode Current	T_C=25°C	I_F	150	A
	T_C=100°C		75	
Diode forward peak surge current		I_{FSM}	300	A
Short-circuit time(V_{GE}=15V, V_{CC}=300V)		Tsc	10	μs
Maximum Power Dissipation (T_C=25°C)		P_D	416	W
Operating Junction Temperature		T_J	-55～+150	°C
Storage Temperature Range		T_{stg}	-55～+150	°C

THERMAL CHARACTERISTICS

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Thermal Resistance, Junction to Case (IGBT)	$R_{\theta JC}$	--	--	--	0.30	°C/W
Thermal Resistance, Junction to Case (FRD)	$R_{\theta JC}$	--	--	--	0.65	°C/W
Thermal Resistance, Junction to Ambient (IGBT)	$R_{\theta JA}$	--	--	--	40	°C/W
Soldering Temperature (in line)	T_{sold}	15^{+2}_{-0} sec, 1time	--	--	260	°C

ELECTRICAL CHARACTERISTICS OF IGBT (T_C=25°C, UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Units
Collector to Emitter Breakdown Voltage	BV_{CE}	V_{GE}=0V, I_C=250μA	650	--	--	V
C-E Leakage Current	I_{CES}	V_{CE}=650V, V_{GE}=0V	--	--	200	μA
G-E Leakage Current	I_{GES}	V_{GE}=20V, V_{CE}=0V	--	--	±400	nA
G-E Threshold Voltage	$V_{GE(th)}$	I_C=250μA, V_{CE}=V_{GE}	4.0	5.0	7	V
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	I_C=75A, V_{GE}=15V, T_C=25°C	--	1.65	--	V
		I_C=75A, V_{GE}=15V, T_C=125°C	--	1.90	--	V
Input Capacitance	C_{ies}	V_{CE}=30V V_{GE}=0V f=1MHz	--	4200	--	pF
Output Capacitance	C_{oes}		--	300	--	
Reverse Transfer Capacitance	C_{res}		--	83	--	
Turn-On Delay Time	$T_{d(on)}$	V_{CE}=400V I_C=75A R_g=10Ω V_{GE}=15V Inductive load T_C=25°C	--	55	--	ns
Rise Time	T_r		--	42	--	
Turn-Off Delay Time	$T_{d(off)}$		--	210	--	
Fall Time	T_f		--	90	--	
Turn-On Switching Loss	E_{on}		--	1.07	--	mJ
Turn-Off Switching Loss	E_{off}		--	1.70	--	
Total Switching Loss	E_{st}		--	2.77	--	
Turn-On Delay Time	$T_{d(on)}$	V_{CE}=400V I_C=37.5A R_g=10Ω V_{GE}=15V inductive load T_C=25°C	--	43	--	ns
Rise Time	T_r		--	24	--	
Turn-Off Delay Time	$T_{d(off)}$		--	230	--	
Fall Time	T_f		--	48	--	
Turn-On Switching Loss	E_{on}		--	0.40	--	mJ
Turn-Off Switching Loss	E_{off}		--	0.88	--	
Total Switching Loss	E_{st}		--	1.28	--	
Total Gate Charge	Q_g	V_{CE}=400V, I_C=75A, V_{GE}=15V	--	180	--	nC
Gate to Emitter Charge	Q_{ge}		--	40	--	
Gate to Collector Charge	Q_{gc}		--	80	--	

ELECTRICAL CHARACTERISTICS OF FRD (T_C=25°C UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	V_{FM}	I_F=75A, T_C=25°C	--	1.82	2.3	V
		I_F=75A, T_C=125°C	--	1.52	--	
Diode Reverse Recovery Time	T_{rr}	I_{EC}=75A, dI_{EC}/dt=200A/μs	--	45	--	ns
Diode Reverse Recovery Charge	Q_{rr}	I_{EC}=75A, dI_{EC}/dt=200A/μs	--	135	--	nC

ELECTRICAL CHARACTERISTICS OF IGBT (T_C=125°C)

Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Units
Turn-On Delay Time	$T_{d(on)}$	V_{CE}=400V I_C=75A R_g=10Ω V_{GE}=15V inductive load T_C=125°C	--	49	--	ns
Rise Time	T_r		--	43	--	
Turn-Off Delay Time	$T_{d(off)}$		--	232	--	
Fall Time	T_f		--	117	--	
Turn-On Switching Loss	E_{on}		--	1.28	--	mJ
Turn-Off Switching Loss	E_{off}		--	2.45	--	
Total Switching Loss	E_{st}		--	3.73	--	
Turn-On Delay Time	$T_{d(on)}$	V_{CE}=400V I_C=37.5A R_g=10Ω V_{GE}=15V inductive load T_C=125°C	--	51	--	ns
Rise Time	T_r		--	28	--	
Turn-Off Delay Time	$T_{d(off)}$		--	264	--	
Fall Time	T_f		--	125	--	
Turn-On Switching Loss	E_{on}		--	0.47	--	mJ
Turn-Off Switching Loss	E_{off}		--	1.47	--	
Total Switching Loss	E_{st}		--	1.94	--	

TYPICAL CHARACTERISTICS CURVE

Figure 1. Typical Output Characteristics

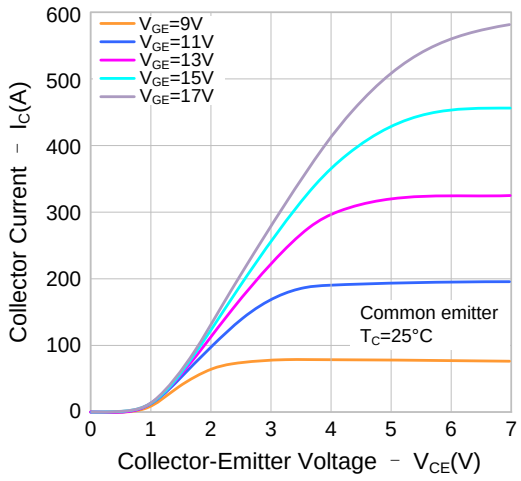


Figure 2. Typical Output Characteristics

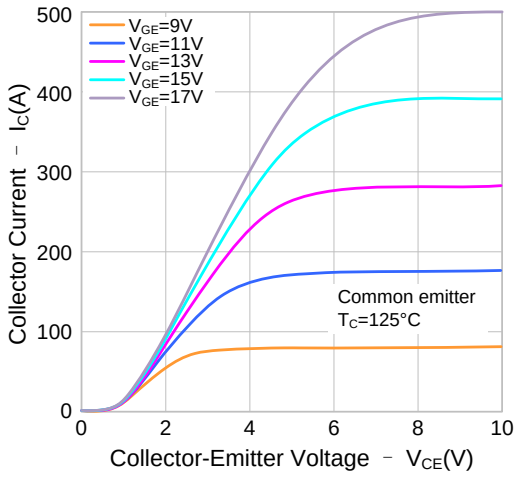


Figure 3. Typical Saturation Voltage Characteristic

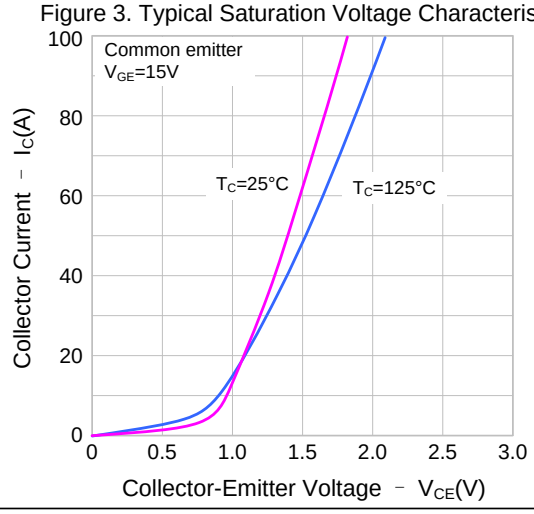


Figure 4. Transfer Characteristic

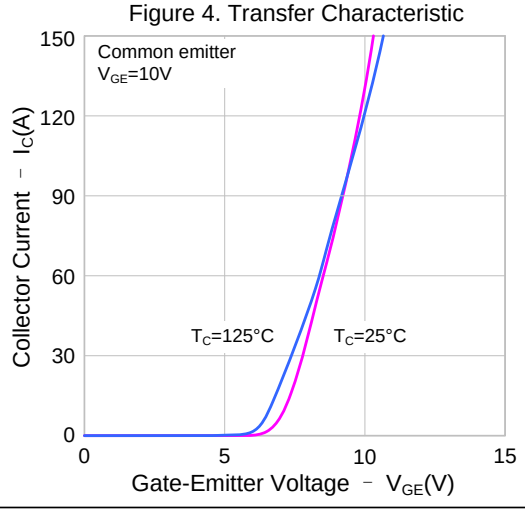


Figure 5. Saturation Voltage vs. V_{GE}

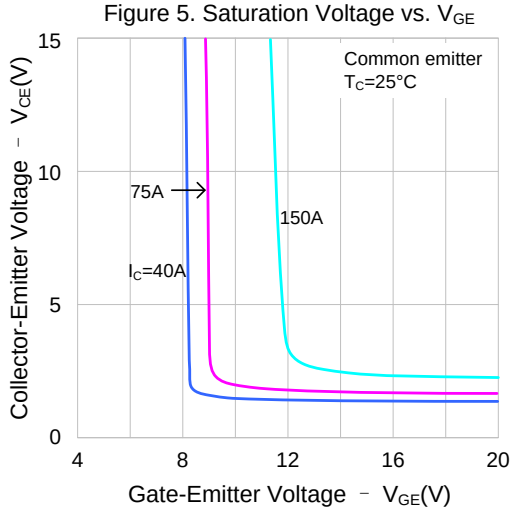
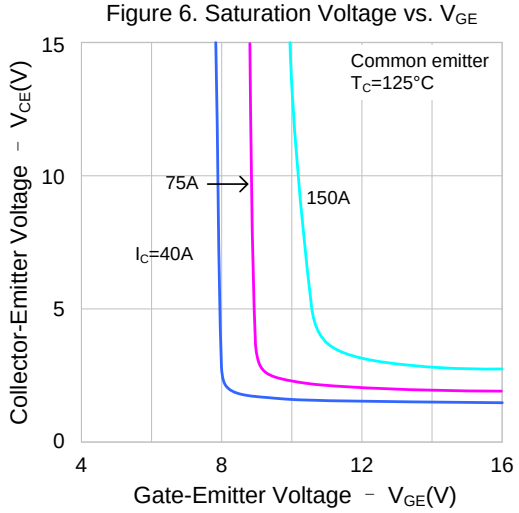


Figure 6. Saturation Voltage vs. V_{GE}



TYPICAL CHARACTERISTICS CURVE (CONTINUED)

Figure 7. Saturation Voltage Drop vs. Temperature

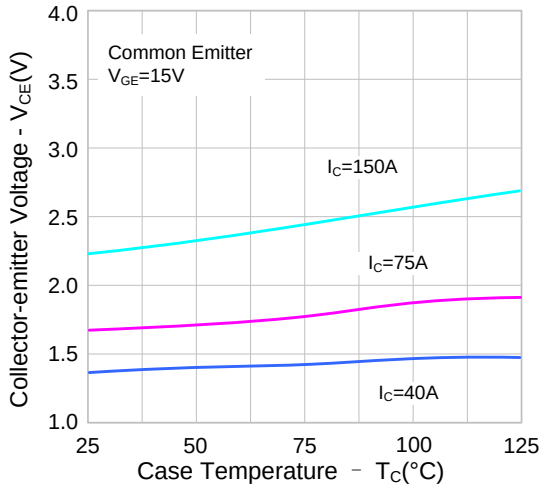


Figure 8. Capacitance Characteristic

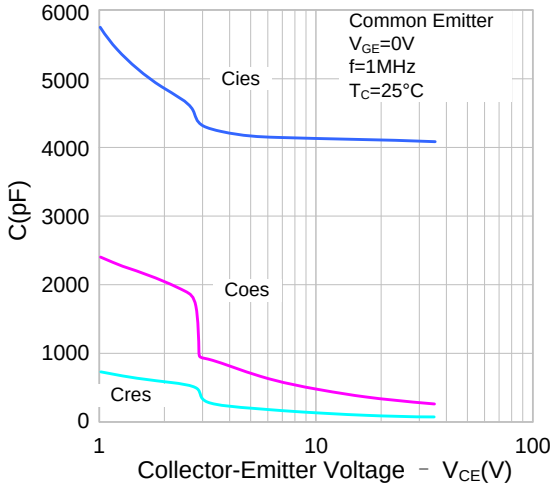


Figure 9. Gate Charge Characteristic

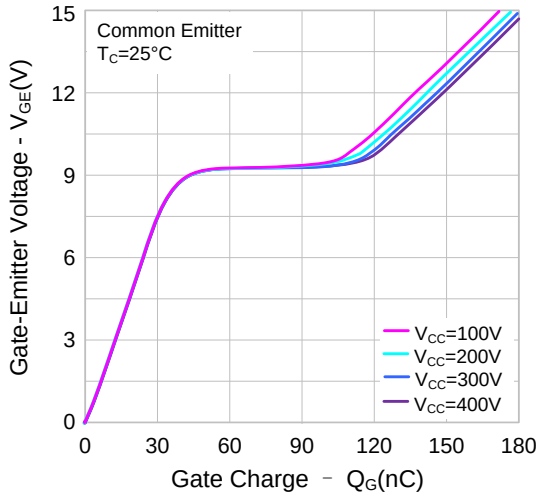


Figure 10. Forward Characteristics

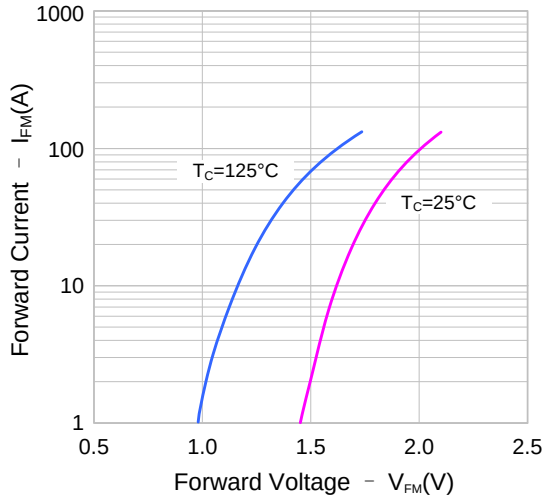


Figure 11. Turn-0n Characteristic vs. Gate Resistance

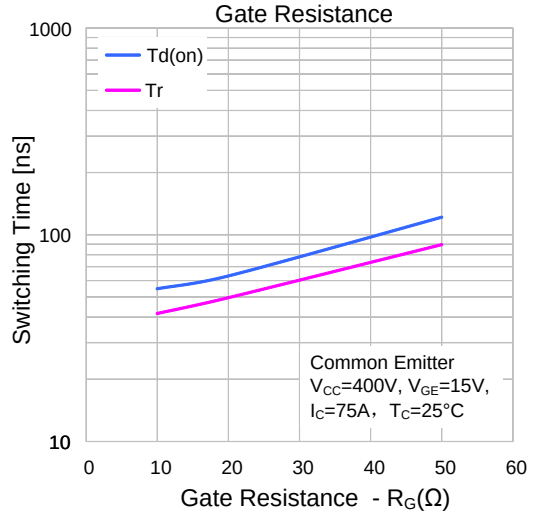
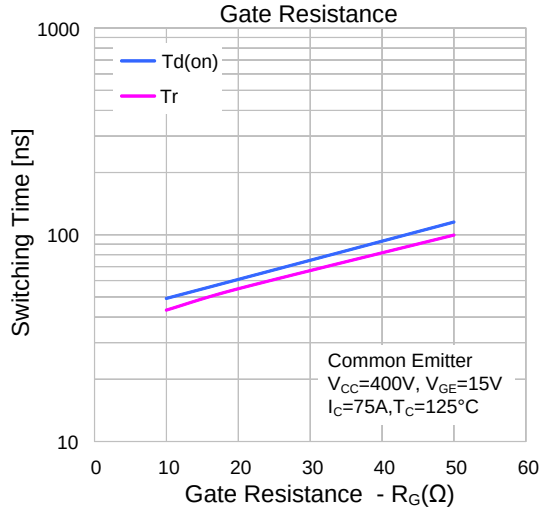


Figure 12. Turn-0n Characteristic vs. Gate Resistance



TYPICAL CHARACTERISTICS CURVE (CONTINUED)

Figure 13. Turn-off Characteristic vs. Gate Resistance

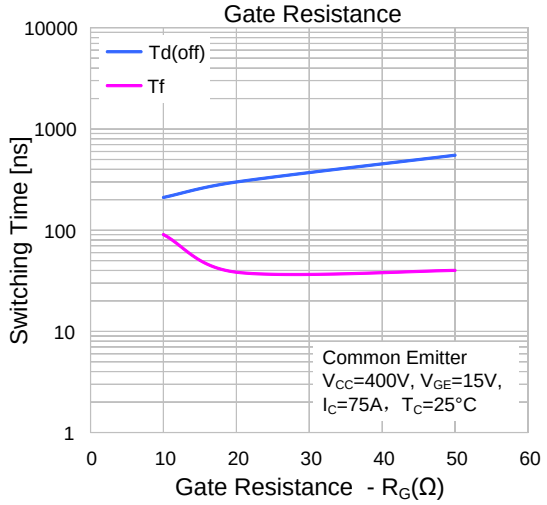


Figure 14. Turn-off Characteristic vs. Gate Resistance

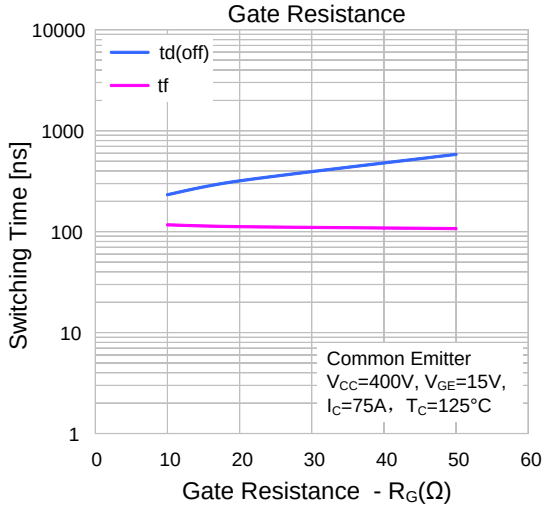


Figure 15. Switching Loss vs. Gate Resistance

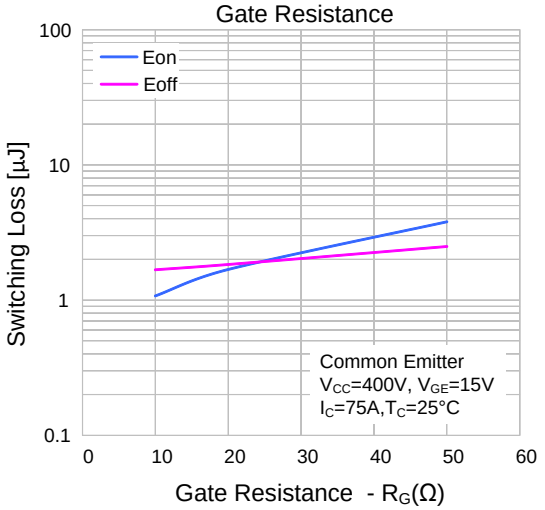


Figure 16. Switching Loss vs. Gate Resistance

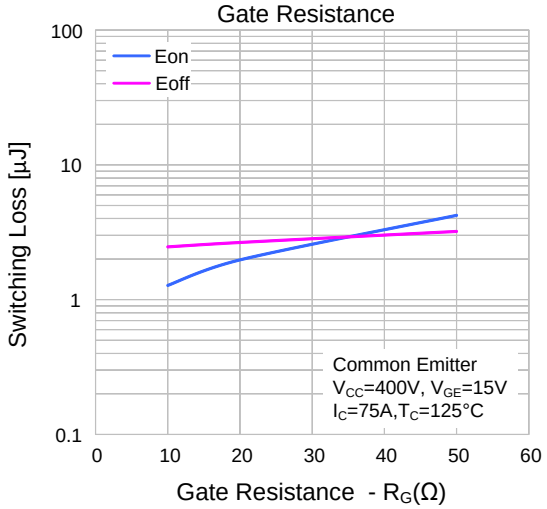


Figure 17. Turn-on Characteristic vs. Collector Current

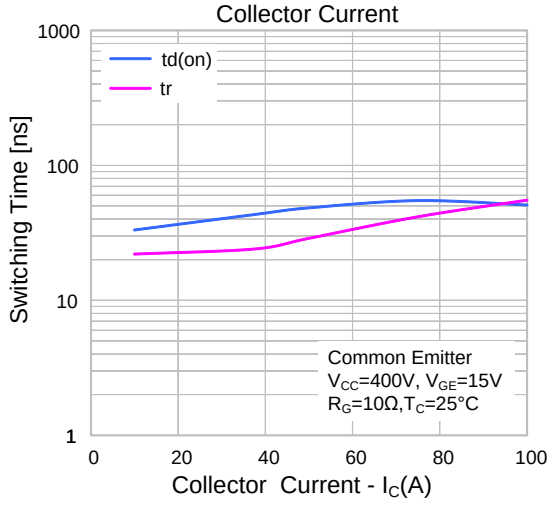
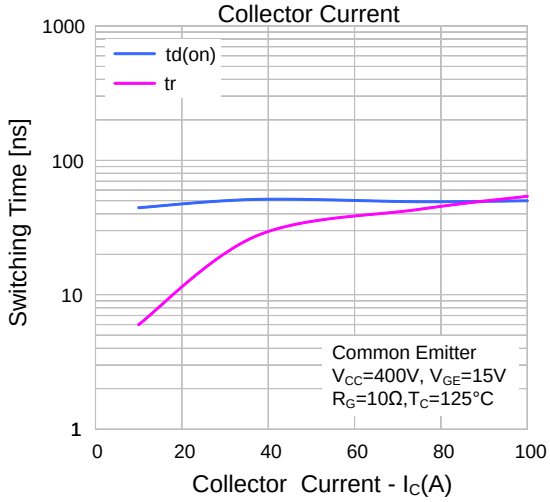


Figure 18. Turn-on Characteristic vs. Collector Current



TYPICAL CHARACTERISTICS CURVE (CONTINUED)

Figure 19. Turn-off Characteristic vs. Collector Current

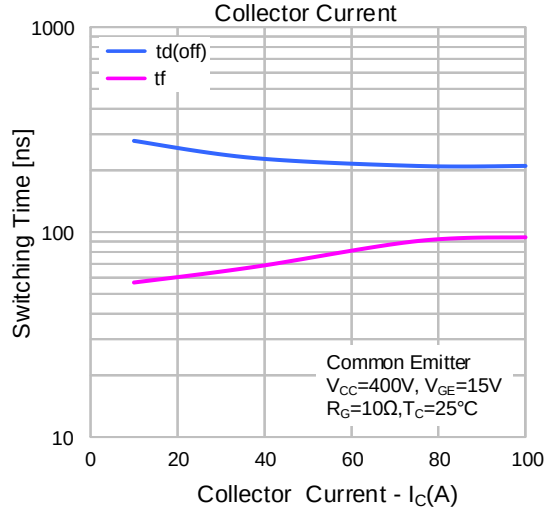


Figure 20. Turn-off Characteristic vs. Collector Current

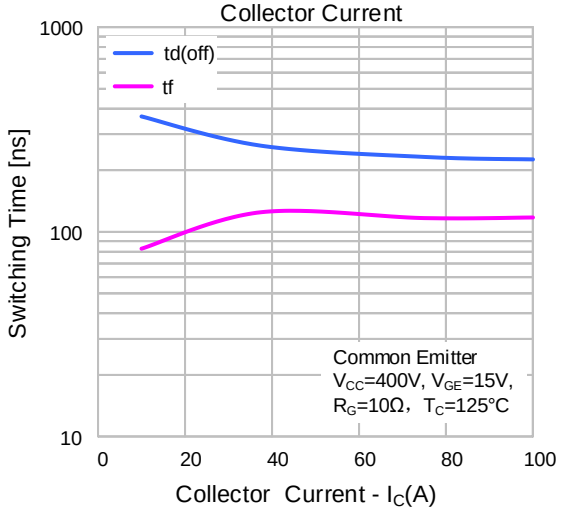


Figure 21. Switching Loss vs. Collector Current

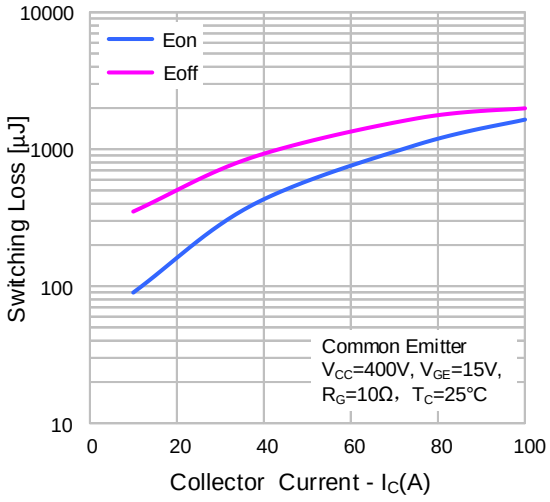


Figure 22. Switching Loss vs. Collector Current

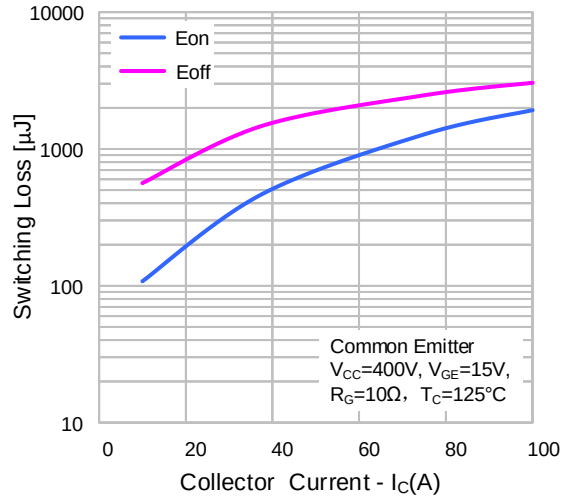


Figure 23. Reverse Recovery Time vs. Forward Current

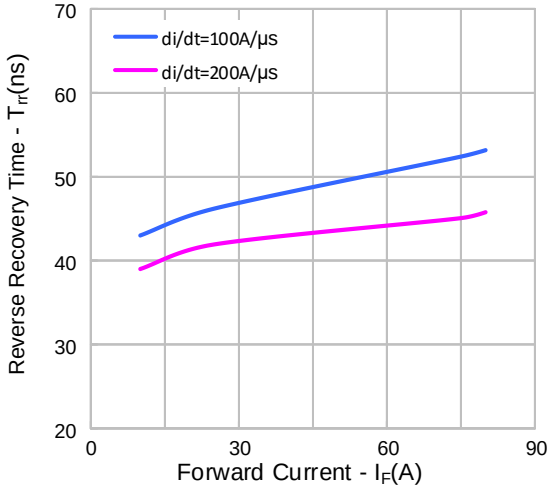
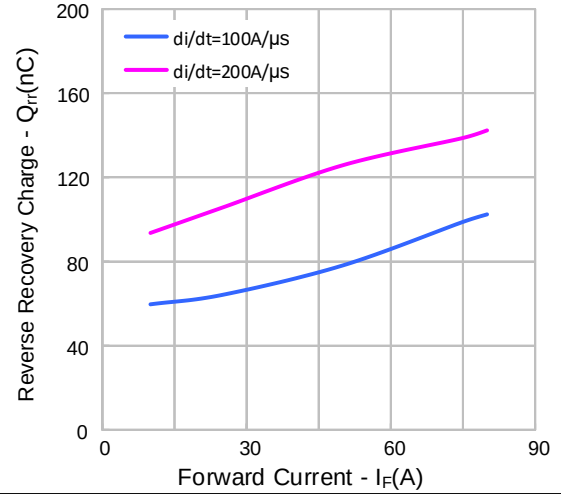


Figure 24. Reverse Recovery Charge vs. Forward Current



TYPICAL CHARACTERISTICS CURVE (CONTINUED)

Figure 25. Peak Reverse Recovery Current vs. Forward Current

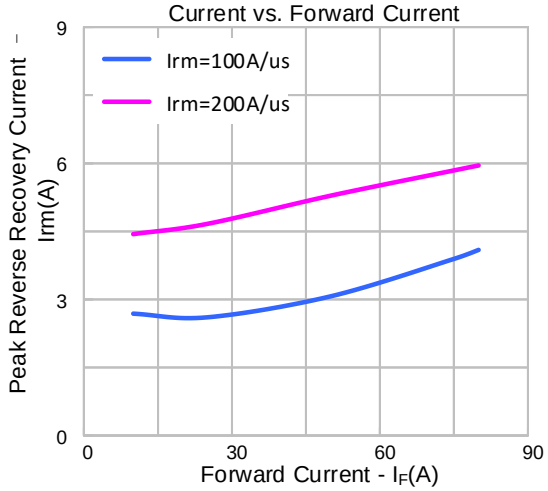


Figure 26. Tb Slope vs. Forward Current

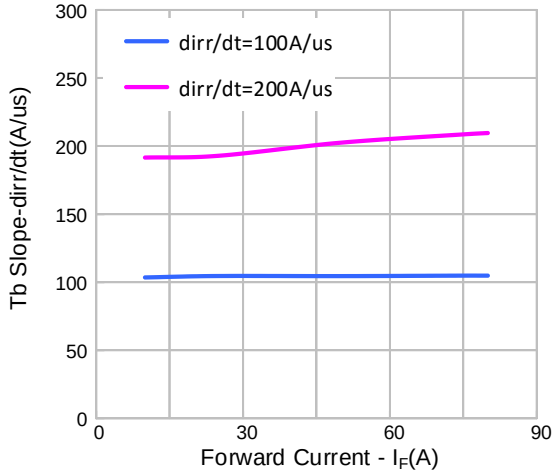


Figure 27. Max. Safe Operating Area

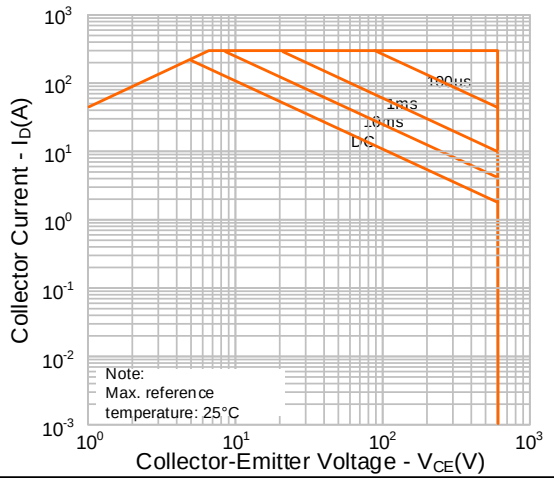


Figure 28. Square Wave Impedance Simulation For All Heating Data Folders(IGBT)

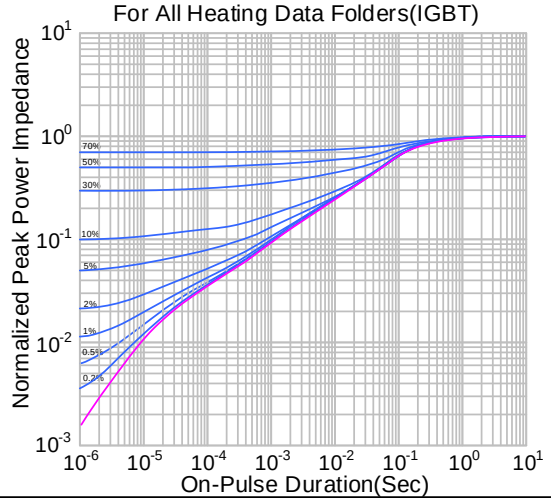
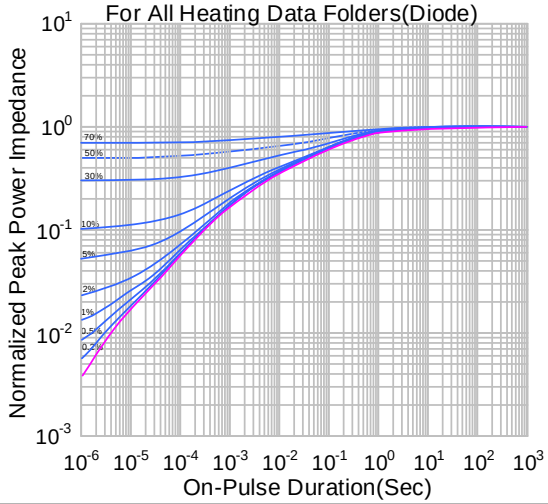
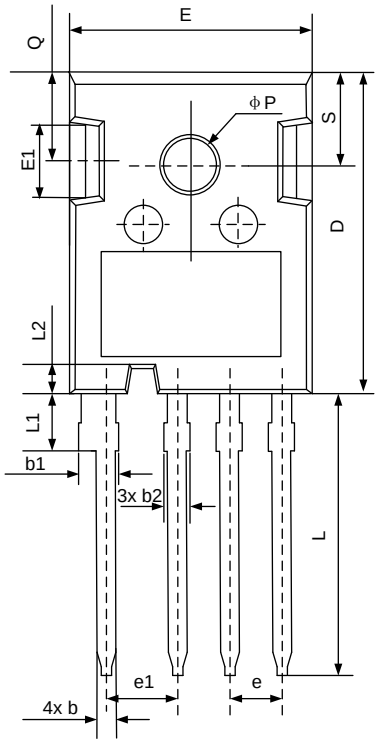


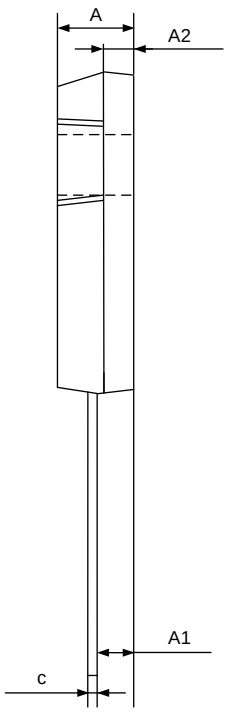
Figure 29. Square Wave Impedance Simulation For All Heating Data Folders(Diode)



PACKAGE OUTLINE

TO-247-4L **UNIT: mm**





SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.83	—	5.21
A1	2.29	—	2.54
A2	1.91	—	2.16
b	1.07	—	1.33
b1	2.39	—	2.94
b2	1.07	—	1.60
c	0.55	—	0.68
D	23.30	—	23.60
E	15.75	—	16.13
E1	3.68	—	5.10
e	2.54 BSC		
e1	5.08 BSC		
L	17.31	—	17.82
L1	3.97	—	4.37
L2	2.35	—	2.65
P	3.51	—	3.65
Q	5.49	—	6.00
S	6.04	—	6.30

Important notice :

1. **The instructions are subject to change without notice!**
2. **Customers should obtain the latest relevant information before placing orders and should verify that such information is complete and current. Please read the instructions carefully before using our products, including the circuit operation precautions.**
3. **Our products are consumer electronic products or the other civil electronic products.**
4. **When using our products, please do not exceed the maximum rating of the products, otherwise the reliability of the whole machine will be affected. There is a certain possibility of failure or malfunction of any semiconductor product under specific conditions. The buyer is responsible for complying with safety standards and taking safety measures when using our products for system design, sample and whole machine manufacturing, so as to avoid potential failure risk that may cause personal injury or property loss.**
5. **It is strongly recommended to identify the trademark when buying our products. Please contact us if there is any question.**
6. **Product promotion is endless, our company will wholeheartedly provide customers with better products!**
7. **Website: http: //www.silan.com.cn**

Part No.:	SGT75T65SDM1P4	Document Type:	Datasheet
Copyright:	HANGZHOU SILAN MICROELECTRONICS CO.,LTD	Website:	http: //www.silan.com.cn

Rev.: 1.3

Revision History:

1. Add I_F when T_C=25°C
2. Update figures 23 and 24, Add figures 25 and 26

Rev.: 1.2

Revision History:

1. Add V_{GE}
2. Modify and add electrical characteristics when T_C=25ºC
3. Add electrical characteristics of IGBT when T_C=125ºC
4. Update typical characteristics curve

Rev.: 1.1

Revision History:

1. Update Datasheet

Rev.: 1.0

Revision History:

1. First release